

REVISION R

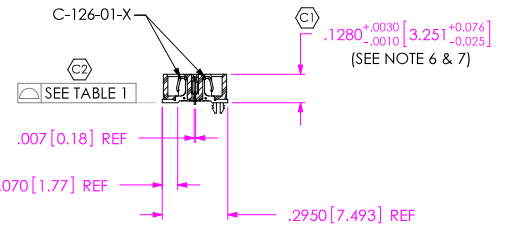
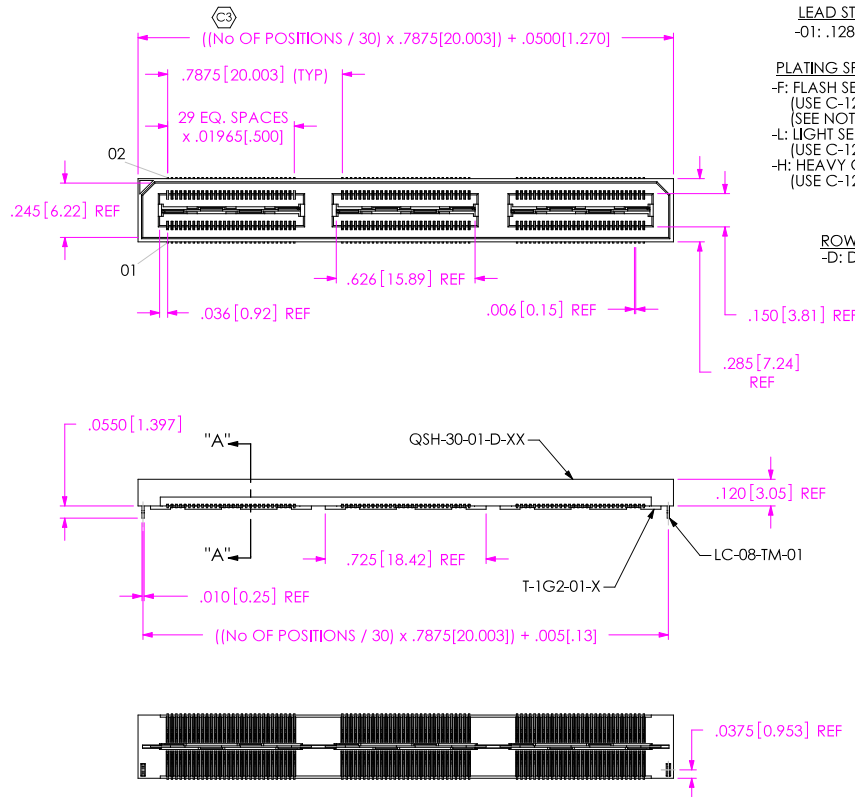
DO NOT SCALE FROM THIS PRINT

QSH-XXX-01-X-D-XX

- No. OF POSITIONS**
 -030, -060, -090, -120, -150 (PER ROW)
- LEAD STYLE**
 -01: .1280[3.25]
- PLATING SPECIFICATION**
 -F: FLASH SELECTIVE GOLD (USE C-126-01-F, T-1G2-01-F) (SEE NOTE 8)
 -L: LIGHT SELECTIVE GOLD (USE C-126-01-L, T-1G2-01-G)
 -H: HEAVY GOLD (USE C-126-01-H, T-1G2-01-G)
- ROW SPECIFICATION**
 -D: DOUBLE (USE QSH-30-01-D-XX)
- OPTION**
 -A: ALIGNMENT PINS (USE QSH-30-01-D-XX-A, SEE FIG. 2)
 -LC: LOCKING CLIPS (USE LC-08-TM-01)
 -GP: GUIDE POSTS (USE QSH-30-01-D-XX-GP) (SEE FIG. 4, SHEET 3) (TAPE & REEL FOR -GP, 60 POS MAX)
 -K: POLYAMIDE FILM PAD (USE K-850-650, SEE FIG. 3)
 -TR: TAPE & REEL (90 POS MAX)
 -TY: TRAY PACKAGING (NOT AVAILABLE WITH -TR)
 -FL: FRICTION LOCKS (SEE FIG. 5, SHEET 3) (NOT AVAILABLE WITH -GP)
 -RT1: RETENTION (MUST USE -A OPTION) (USE QSH-30-01-D-XX-A-RT1 & SUB-SC-05-01-FF) (SEE FIG. 6, SHEET 3) (NOT AVAILABLE WITH -LC, -GP, OR -FL) (NOT AVAILABLE WITH -120 & -150 POS)
- No OF BANKS** R

FIG. 1

-LC: LOCKING CLIP OPTION SHOWN



SECTION "A"- "A"

- NOTES:
 1. $\text{\textcircled{C}}$ REPRESENTS A CRITICAL DIMENSION.
 2. NOTE DELETED.
 3. CONTACT RETENTION: 8 OZ. MINIMUM.
 4. GROUND PLANE RETENTION: 8 OZ. MINIMUM.
 5. BURR ALLOWANCE: .0015[.038] MAX.
 6. MAX VARIANCE: .002[.05].
 7. DIMENSION APPLIES TO CONTACT & GROUND PLANE.
 8. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING.
 -G PLATED GROUND PLANE CAN BE SUBSTITUTED FOR -F PLATED GROUND PLANE.
 9. SUB-SC-05-01-XX RETENTION TO BE 1.0 LBF IN BODY.

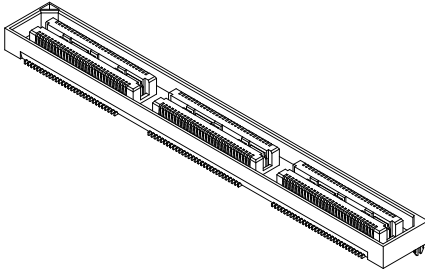


TABLE 1	
No OF POS	COPLANARITY INCLUDING GROUND PLANE
-030 THRU -060	.0040[.102]
-090 THRU -150	.0060[.152]

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE:
 DECIMALS ANGLES
 .XX: $\pm 0.1[3]$ 2°
 .XXX: $\pm 0.005[.13]$
 .XXXX: $\pm 0.0020[.051]$

SAMTEC
 520 PARK EAST BLVD, NEW ALBANY, IN 47150
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 e-Mail: INFO@SAMTEC.COM CODE: 55322

MATERIAL: DO NOT SCALE DRAWING	SHEET SCALE: 1:5:1	DESCRIPTION: .5mm DOUBLE ROW HS SOCKET ASSEMBLY
INSULATOR: BLACK LCP CONTACT & GROUND PLANE: PHOS BRONZE		DWG. NO.: QSH-XXX-01-X-D-XX
F:\DWG\MBC\MKTG\QSH-XXX-01-X-D-XX-MKT.SLDRW		BY: DEAN P 05/21/1999 SHEET 1 OF 3

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FIG. 2
-A: ALIGNMENT PIN OPTION

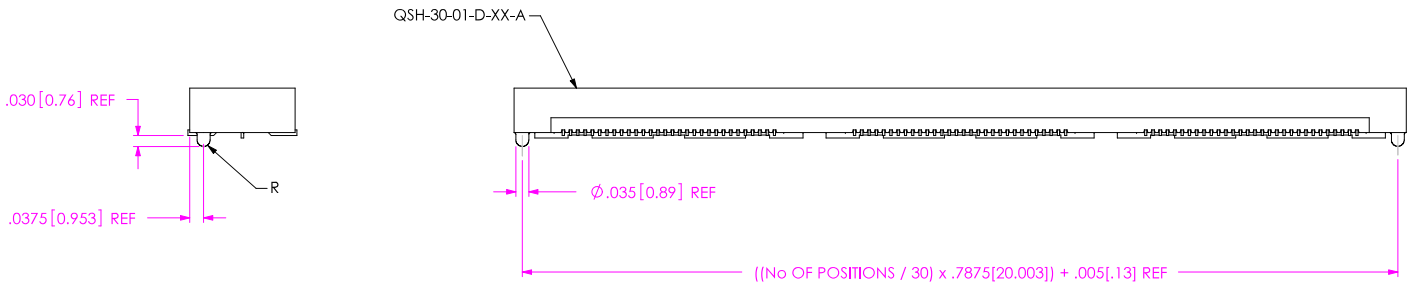
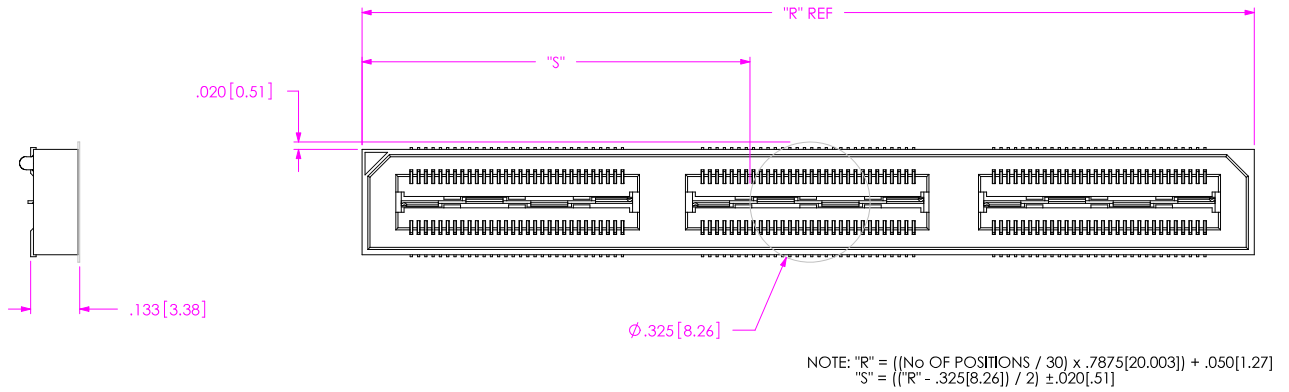


FIG. 3
-K: POLYAMIDE FILM PAD
[USE K-850-650]



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SHEET SCALE: 2:1

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DWG. NO. QSH-XXX-01-X-D-XX

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FIG. 4
 -GP: GUIDE POSTS
 (SAME AS FIG. 1, UNLESS OTHERWISE STATED)

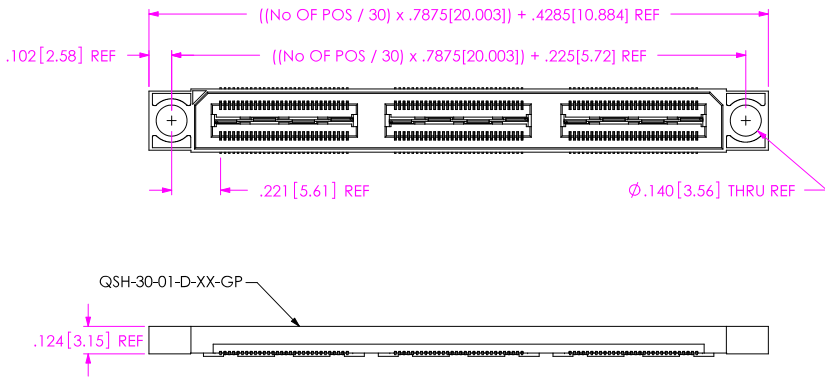
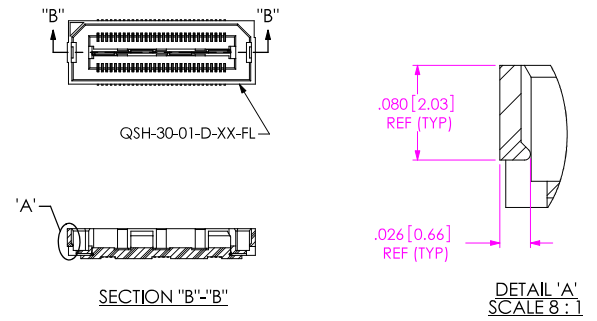


FIG. 5
 -FL: FRICTION LOCKS
 (NOT AVAILABLE WITH -GP OPTION)
 (SAME AS FIG. 1, UNLESS OTHERWISE STATED)



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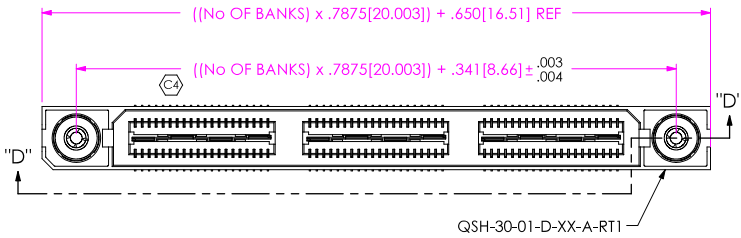
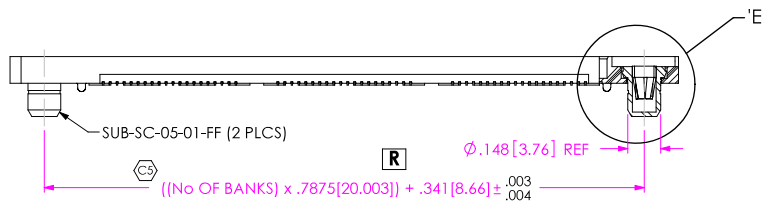
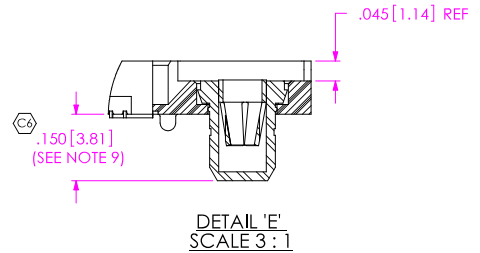


FIG. 6
 -RT1: RETENTION OPTION
 (MUST USE -A OPTION)
 (NOT AVAILABLE WITH -LC, -GP, OR -FL OPTIONS)
 (NOT AVAILABLE WITH -120 & -150 POS)
 (SAME AS FIG. 1, UNLESS OTHERWISE STATED)



SECTION "D"- "D"
 SCALE 1.5 : 1

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BY: DEAN P 05/21/1999 SHEET 3 OF 3